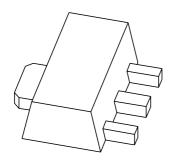
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BFQ591**NPN 7 GHz wideband transistor

Product specification Supersedes data of 2002 Jan 07 2002 Feb 04





# NPN 7 GHz wideband transistor

**BFQ591** 

#### **FEATURES**

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

# **APPLICATIONS**

Intended for applications in the GHz range such as MATV or CATV amplifiers and RF communications subscribers equipment.

## **DESCRIPTION**

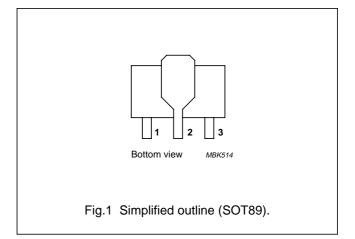
NPN wideband transistor in a SOT89 plastic package.

## **MARKING**

TYPE NUMBER	MARKING CODE
BFQ591	ВСр

#### **PINNING**

PIN	DESCRIPTION
1	emitter
2	collector
3	base



# **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	_	20	V
$V_{CEO}$	collector-emitter voltage	open base	_	_	15	V
I <sub>C</sub>	collector current (DC)		_	_	200	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> ≤ 90 °C; note 1	_	_	2.25	W
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 70 mA; V <sub>CE</sub> = 8 V	60	90	250	
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = 12 V; f = 1 MHz	_	0.8	_	pF
f⊤	transition frequency	$I_C = 70 \text{ mA}; V_{CE} = 12 \text{ V};$ f = 1 GHz	_	7	_	GHz
G <sub>UM</sub>	maximum unilateral power gain	I <sub>C</sub> = 70 mA; V <sub>CE</sub> = 12 V; f = 900 MHz; T <sub>amb</sub> = 25 °C	_	11	_	dB
S <sub>21</sub>   <sup>2</sup>	insertion power gain	I <sub>C</sub> = 70 mA; V <sub>CE</sub> = 12 V; f = 900 MHz; T <sub>amb</sub> = 25 °C	_	10	_	dB

#### Note

1.  $T_s$  is the temperature at the soldering point of the collector pin.

# NPN 7 GHz wideband transistor

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# **LIMITING VALUES**

In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	20	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	3	٧
I <sub>C</sub>	collector current (DC)		_	200	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> ≤ 90 °C; note 1	_	2.25	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	175	°C

## Note

# THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	$T_s \le 90$ °C; note 1	38	K/W

# Note

1.  $T_s$  is the temperature at the soldering point of the collector pin.

<sup>1.</sup>  $T_s$  is the temperature at the soldering point of the collector pin.

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#### **CHARACTERISTICS**

 $T_i = 25$  °C; unless otherwise specified.

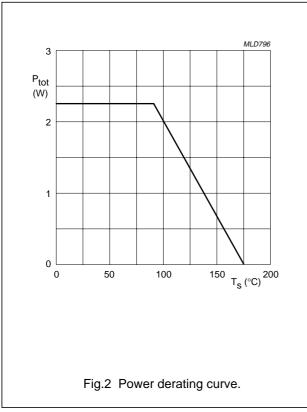
SYMBOL	PARAMETER CONDITIONS		MIN.	TYP.	MAX.	UNIT
V <sub>(BR)CBO</sub>	collector-base breakdown voltage	I <sub>C</sub> = 0.1 mA; I <sub>E</sub> = 0	_	_	20	V
V <sub>(BR)CES</sub>	collector-emitter breakdown voltage	$I_C = 0.1 \text{ mA}; I_B = 0$	_	_	15	V
V <sub>(BR)EBO</sub>	emitter-base breakdown voltage	$I_E = 0.1 \text{ mA}; I_C = 0$	_	_	3	V
I <sub>CBO</sub>	collector-base leakage current	I <sub>E</sub> = 0; V <sub>CB</sub> = 10	-	_	100	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 70 mA ; V <sub>CE</sub> = 8 V	60	90	250	
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = 12 V; f = 1 MHz	_	0.8	_	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 70 mA; V <sub>CE</sub> = 12 V; f = 1 GHz	_	7	_	GHz
G <sub>UM</sub>	maximum unilateral power gain; note 1	$I_C = 70 \text{ mA}; V_{CE} = 12 \text{ V};$ $T_{amb} = 25 \text{ °C}$				
		f = 900 MHz	_	11	-	dB
		f = 2 GHz	_	5.5	-	dB
S <sub>21</sub>   <sup>2</sup>	insertion power gain	I <sub>C</sub> = 70 mA; V <sub>CE</sub> = 12 V; f = 1 GHz; T <sub>amb</sub> = 25 °C	_	10	_	dB
Vo	output voltage	note 2	_	700	_	mV

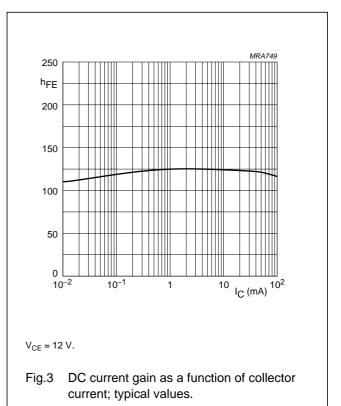
#### **Notes**

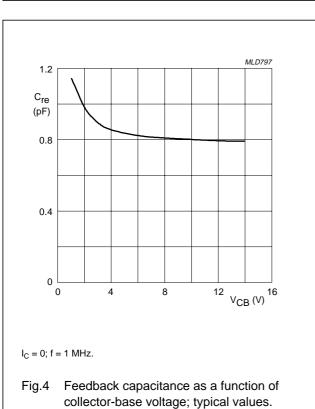
- 1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $s_{12}$  is zero and  $G_{UM} = 10 \log \frac{\left|s_{21}\right|^2}{(1-\left|s_{11}\right|^2)(1-\left|s_{22}\right|^2)} dB$ .
- 2.  $d_{im}$  = 60 dB (DIN45004B);  $V_p = V_o$ ;  $V_q = V_o$  -6 dB;  $f_p$  = 795.25 MHz;  $f_q$  = 803.25 MHz;  $f_r$  = 803.25 MHz; measured at  $f_{(p+q+r)}$  = 793.25 MHz.

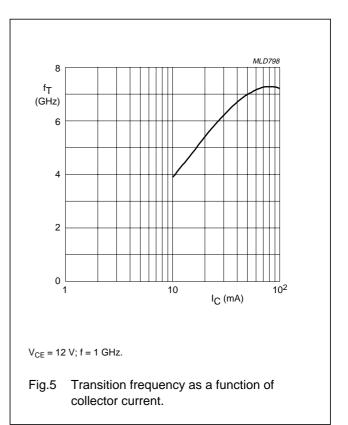
# NPN 7 GHz wideband transistor

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# NPN 7 GHz wideband transistor

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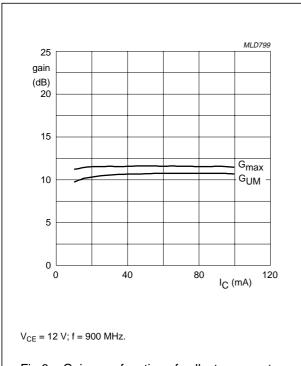
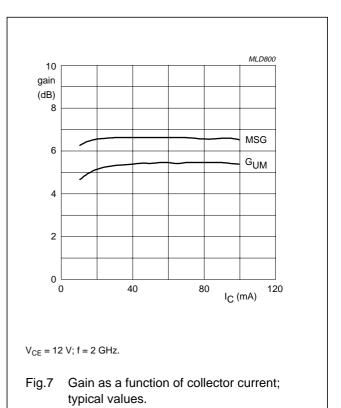
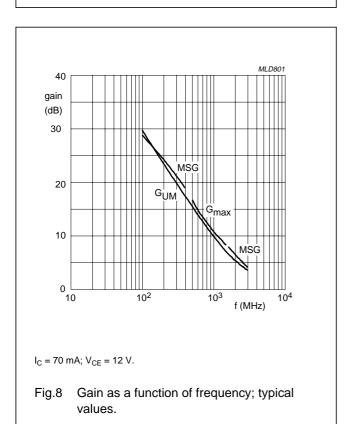


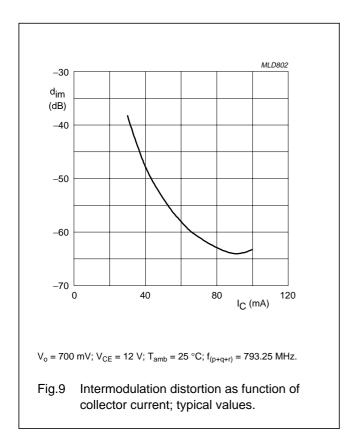
Fig.6 Gain as a function of collector current; typical values.





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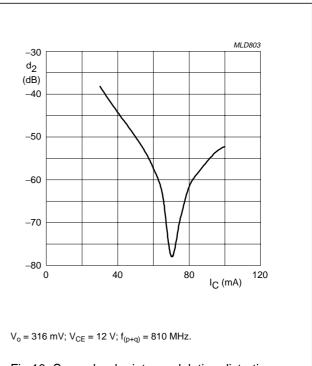


Fig.10 Second order intermodulation distortion as function of collector current; typical values.

2002 Feb 04

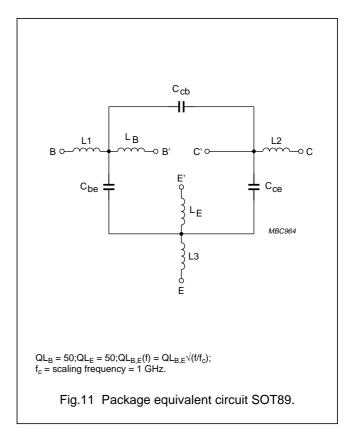
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# NPN 7 GHz wideband transistor

# **BFQ591**

# SPICE parameters for the BFQ591 die.

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	1.341	fA
2	BF	123.5	_
3	NF	.988	_
4	VAF	75.85	V
5	IKF	9.656	mA
6	ISE	232.2	fA
7	NE	2.134	_
8	BR	10.22	_
9	NR	1.016	_
10	VAR	1.992	V
11	IKR	294.1	mA
12	ISC	211.0	аА
13	NC	997.2	_
14	RB	5.00	Ω
15	IRB	1.000	μΑ
16	RBM	5.00	Ω
17	RE	1.275	Ω
18	RC	920.6	Ω
19 <sup>(1)</sup>	XTB	0.000	_
20 <sup>(1)</sup>	EG	1.110	eV
21(1)	XTI	3.000	_
22	CJE	3.821	pF
23	VJE	600.0	mV
24	MJE	348.5	_
25	TF	13.60	ps
26	XTF	71.73	_
27	VTF	10.28	V
28	ITF	1.929	mA
29	PTF	0.000	deg
30	CJC	1.409	fF
31	VJC	219.4	mV
32	MJC	166.5	_
33	XCJ	2.340	-
34	TR	543.7	ps
35 <sup>(1)</sup>	CJS	0.000	F
36 <sup>(1)</sup>	VJS	750.0	mV
37 <sup>(1)</sup>	MJS	0.000	-
38	FC	733.2	



# List of components (see Fig.11)

DESIGNATION	VALUE	UNIT
C <sub>be</sub>	16	fF
C <sub>cb</sub>	150	fF
C <sub>ce</sub>	150	fF
L1	1	nH
L2	0.01	nH
L3	1	nH
L <sub>B</sub>	1.2	nH
L <sub>E</sub>	1.2	nH

# Note

1. These parameters have not been extracted, the default values are shown.

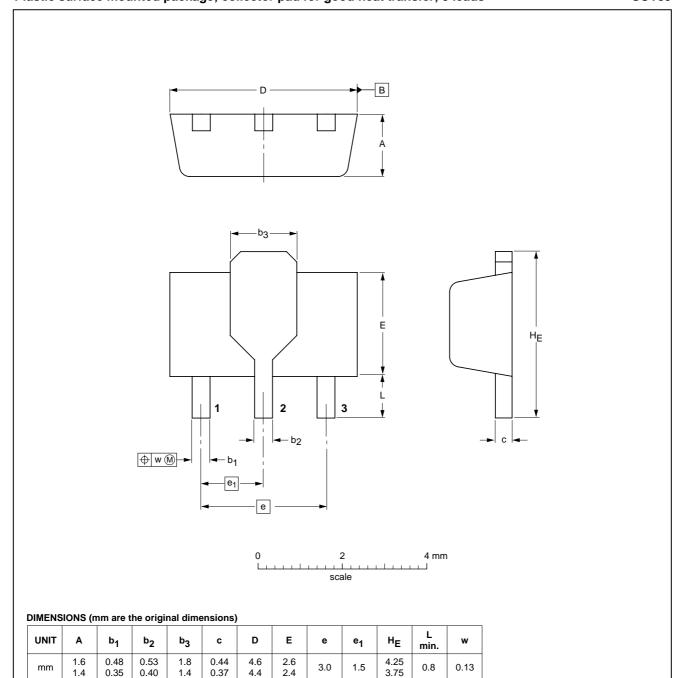
# NPN 7 GHz wideband transistor

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# **PACKAGE OUTLINE**

Plastic surface mounted package; collector pad for good heat transfer; 3 leads

**SOT89** 



OUTLINE		REFERENCES			EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT89		TO-243	SC-62			<del>97-02-28</del> 99-09-13	

# NPN 7 GHz wideband transistor

**BFQ591** 

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DATA SHEET STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
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Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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**NOTES**